



## Customer Information Notification

201501007I

**Issue Date:** 14-Jan-2015  
**Effective Date:** 12-Feb-2015

Here's your personalized quality information concerning products Digi-Key purchased from NXP.  
For detailed information we invite you to view this notification online



# QUALITY

### Management Summary

Package Outline Drawing of SOT975B and SOT975C packages contains wrong value range for package height. Documentation will be updated to reflect the correct values.

### Change Category

<input type="checkbox"/> Wafer Fab process	<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input checked="" type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

Correction of type error in package height spec of SOT975B and SOT975C package

### Information Notification

Current Package Outline Drawing (POD) of product types using SOT975B or SOT975C packages contains an error in the dimensions for package height range.

Mentioned package height range (A) in POD for SOT975B and SOT975C is 3.05-3.63mm.

Correct value for package height range (A) is 2.59-3.15mm.

As example the current (wrong) version and the correct version of the POD for SOT975C are added to this Change Information Note.

### Why do we issue this Information Notification

To inform customers on the correct value of the package height range of SOT975B and SOT975C

### Identification of Affected Products

Product identification does not change

### Impact

no impact to the product's functionality anticipated.

Change affects only the documentation. There is no change to the product.

### Data Sheet Revision

A new datasheet will be issued

### Disposition of Old Products

not relevant

### Remarks

Datasheets of affected products are already updated.

Datasheets are available via the NXP website ([www.nxp.com](http://www.nxp.com))

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

**Name** Hans Buis  
**Position** Process Improvement Manager  
**e-mail address** Hans.Buis@nxp.com

At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards.

Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#	Customer Part#	Changed Part Description
BLF6G27-10G,112	BLF6G27-10G,112	WIMAX RF POWER TRANSISTOR 2.7 GHZ